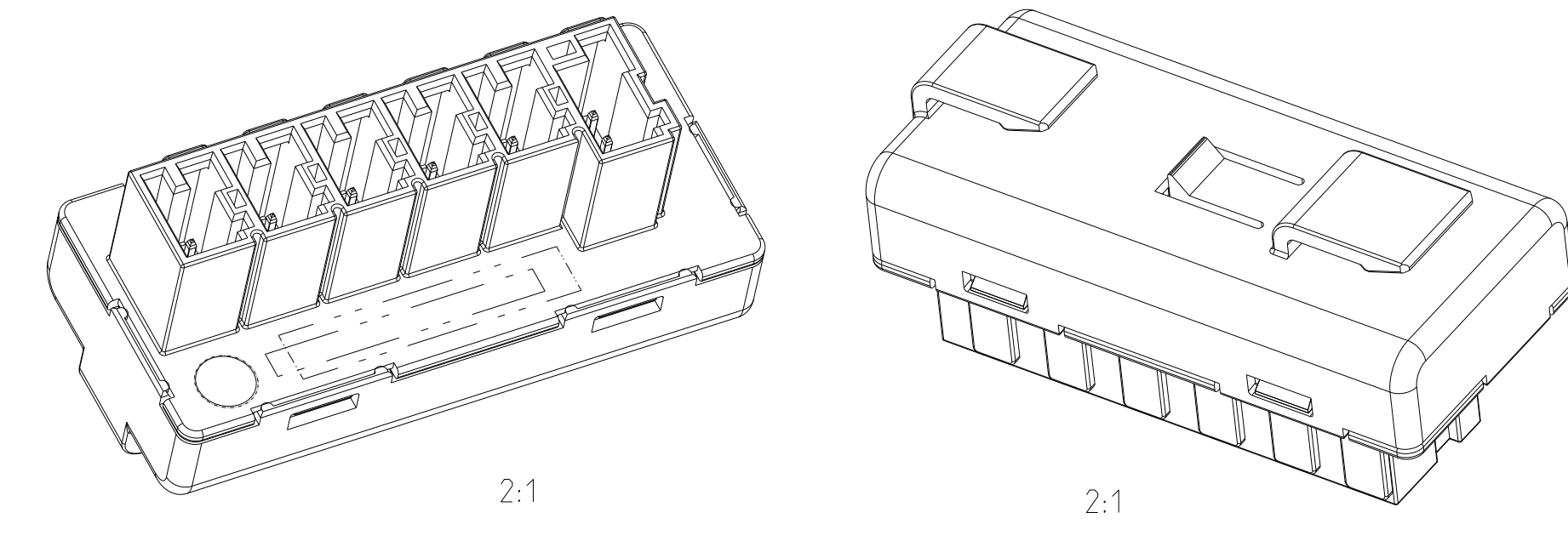
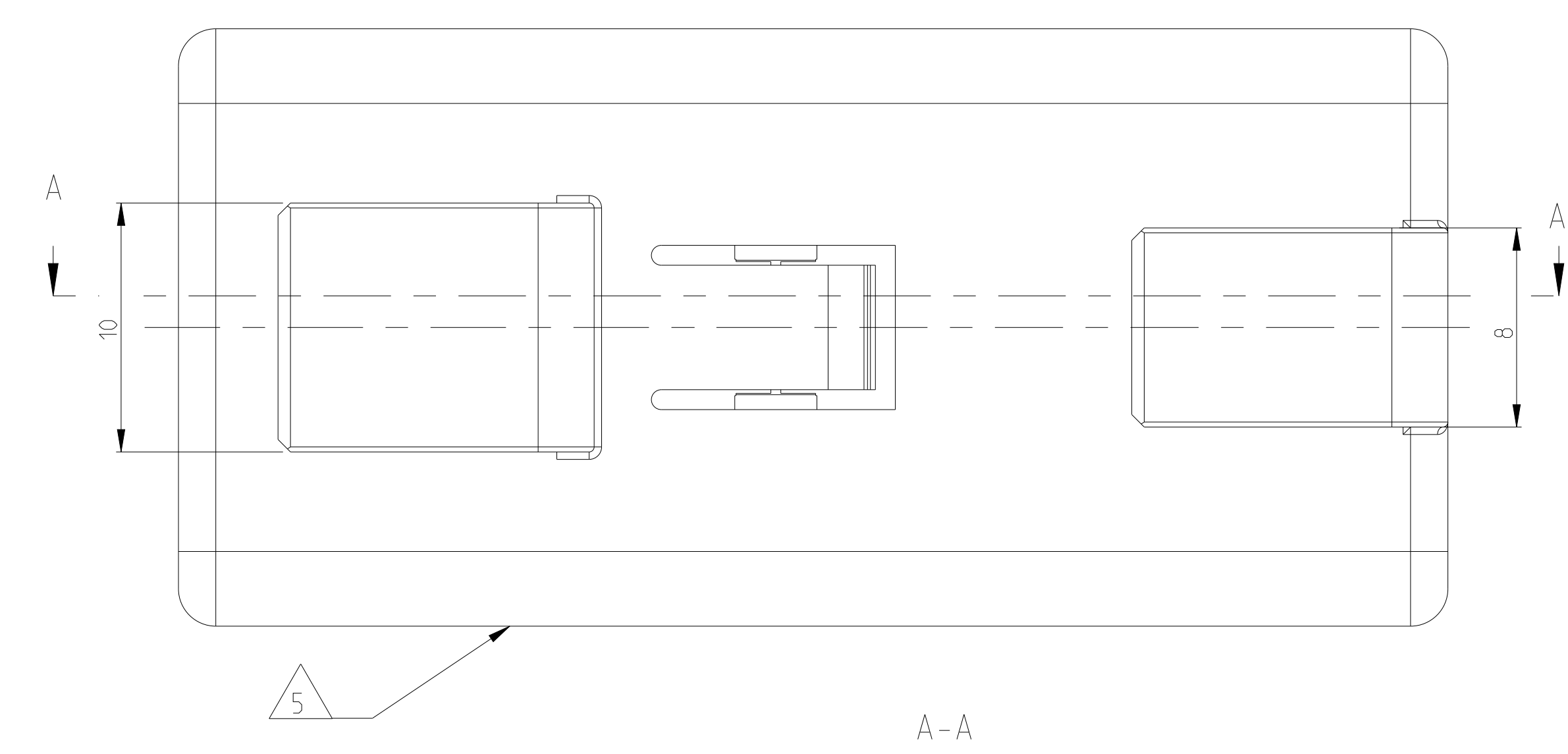
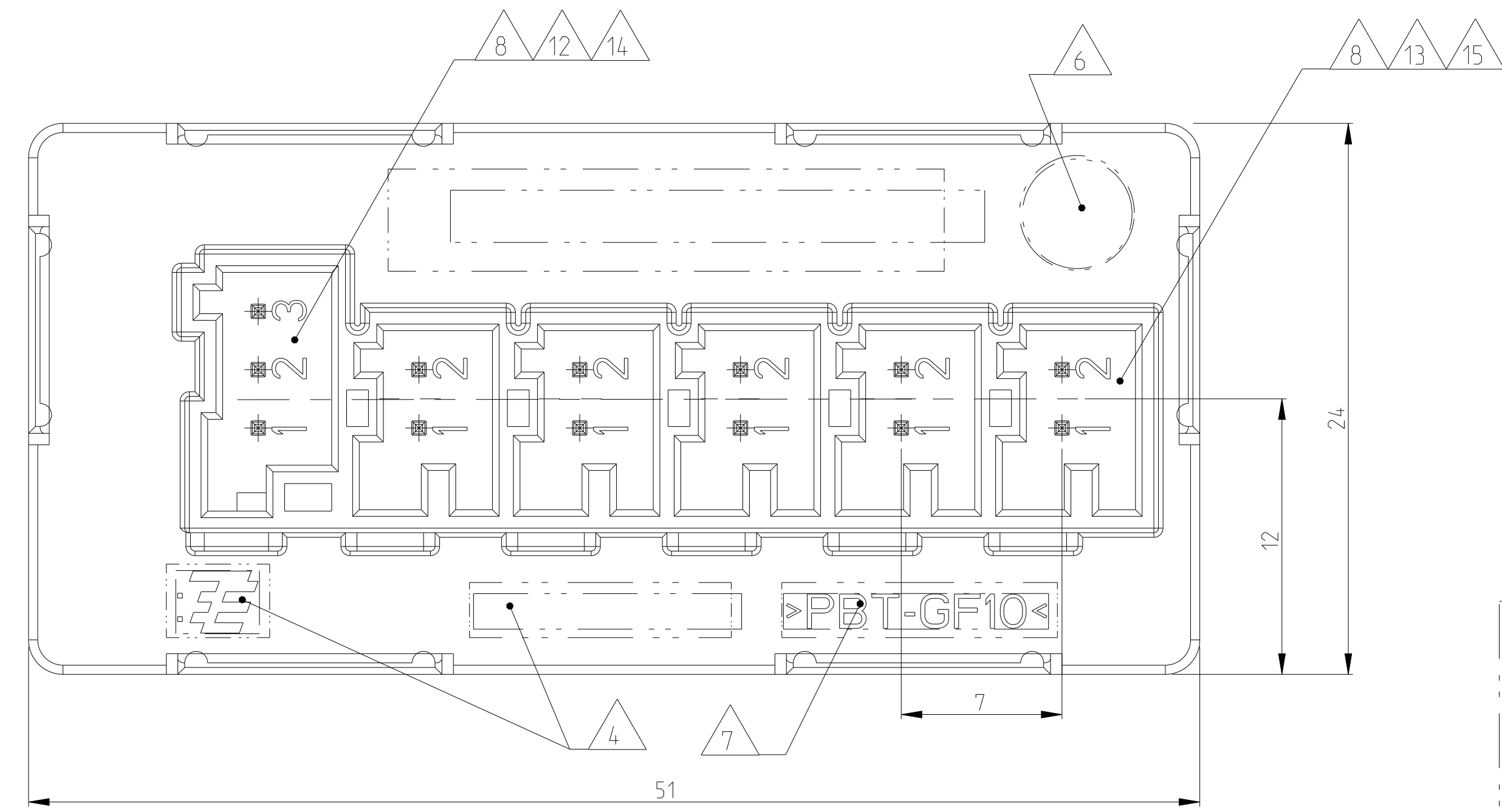
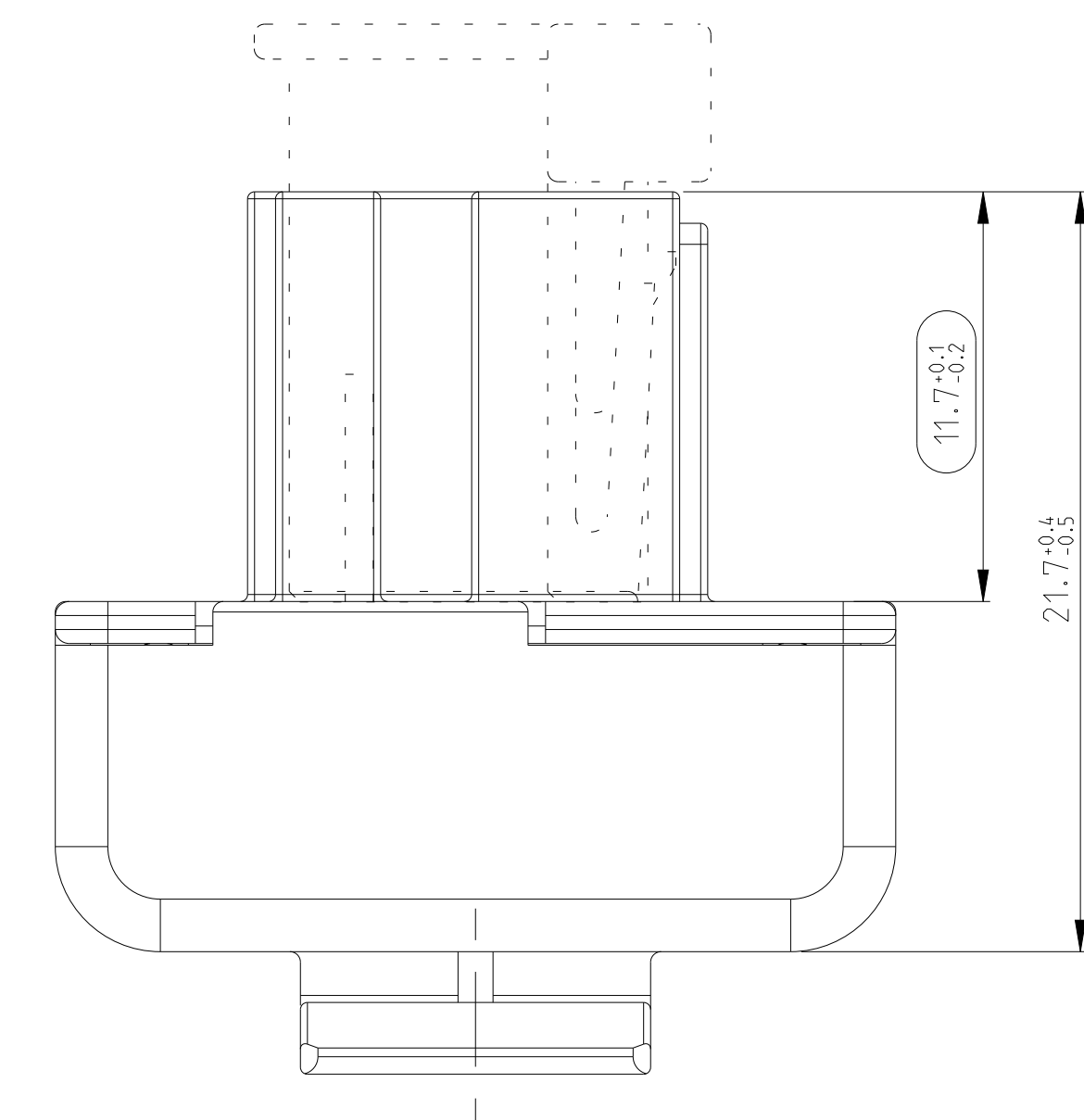
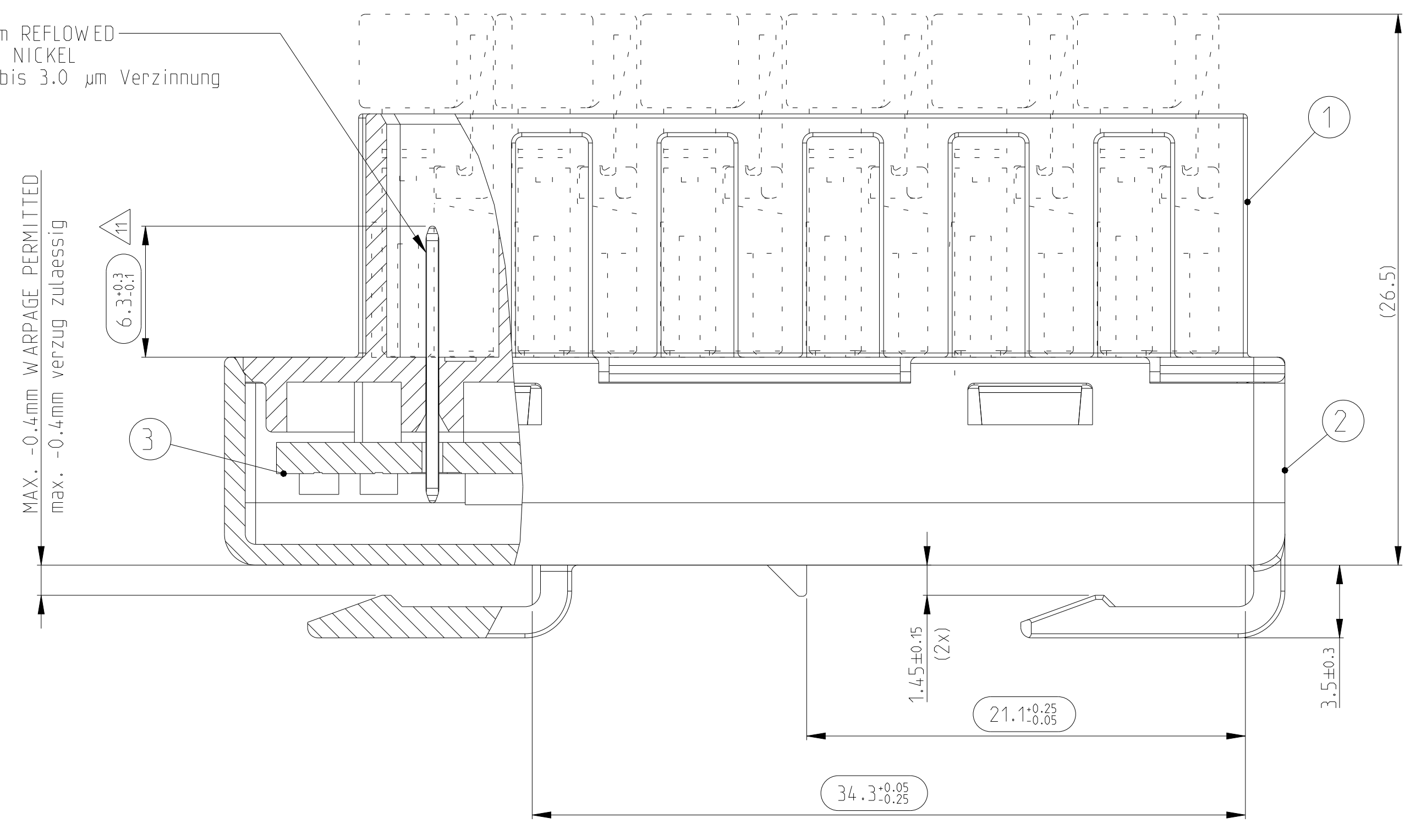


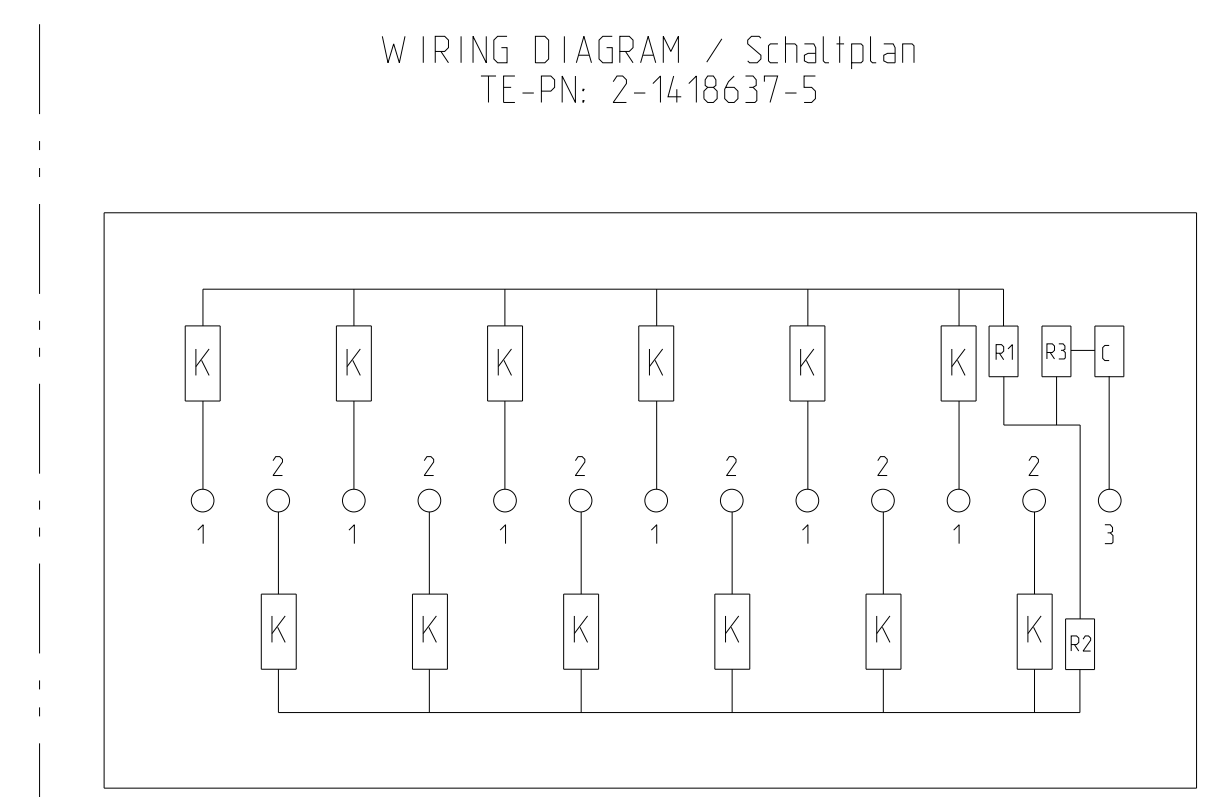
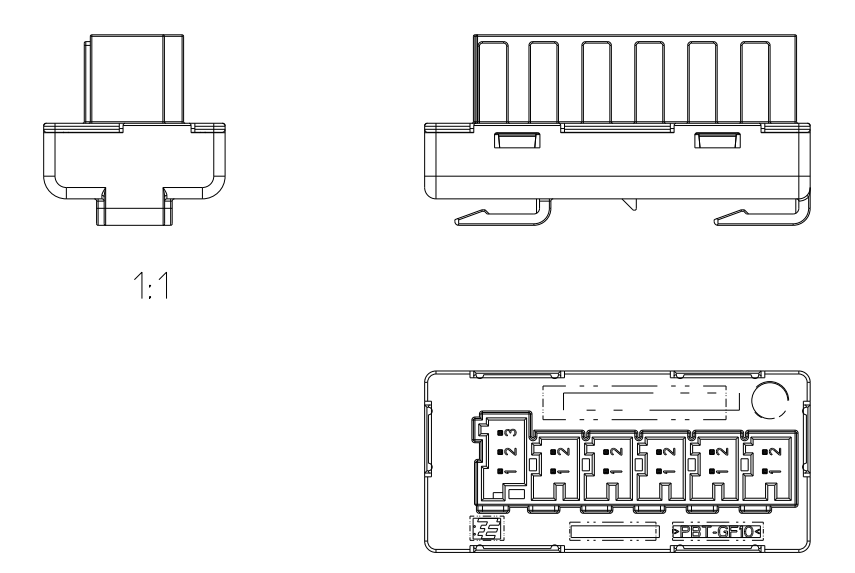
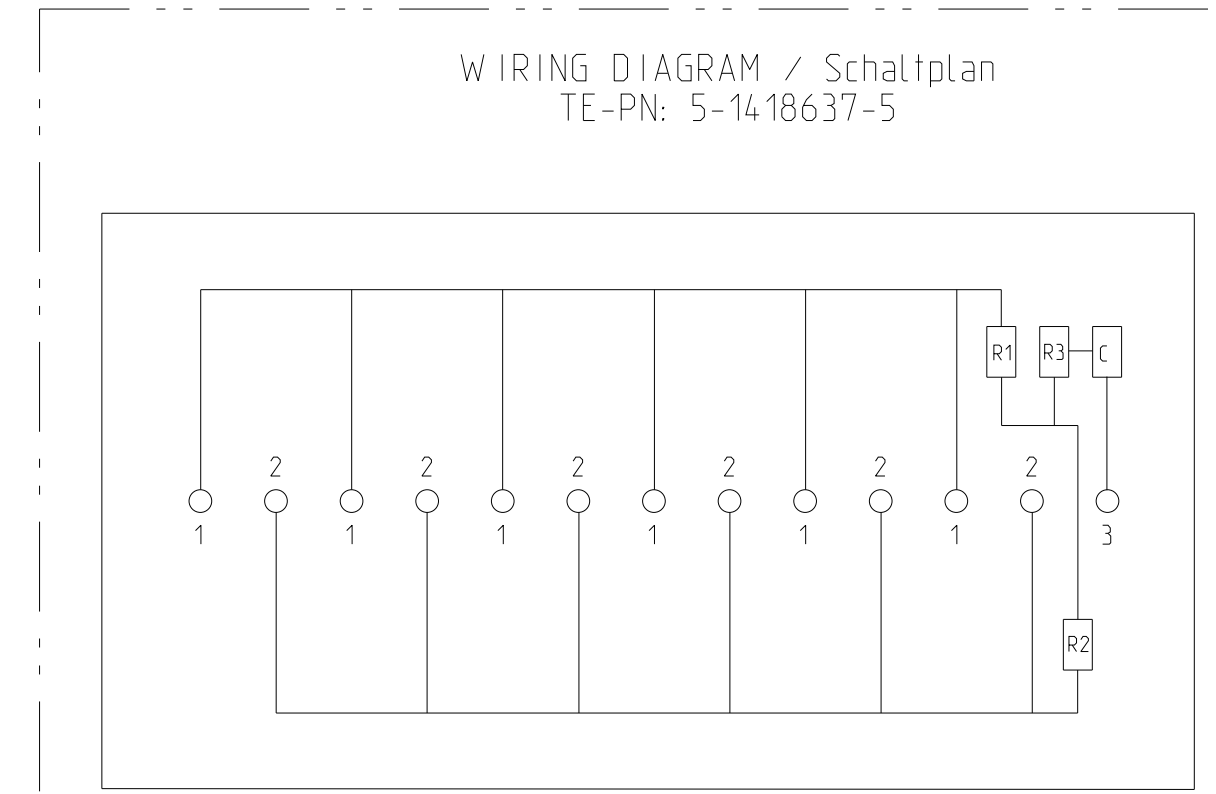
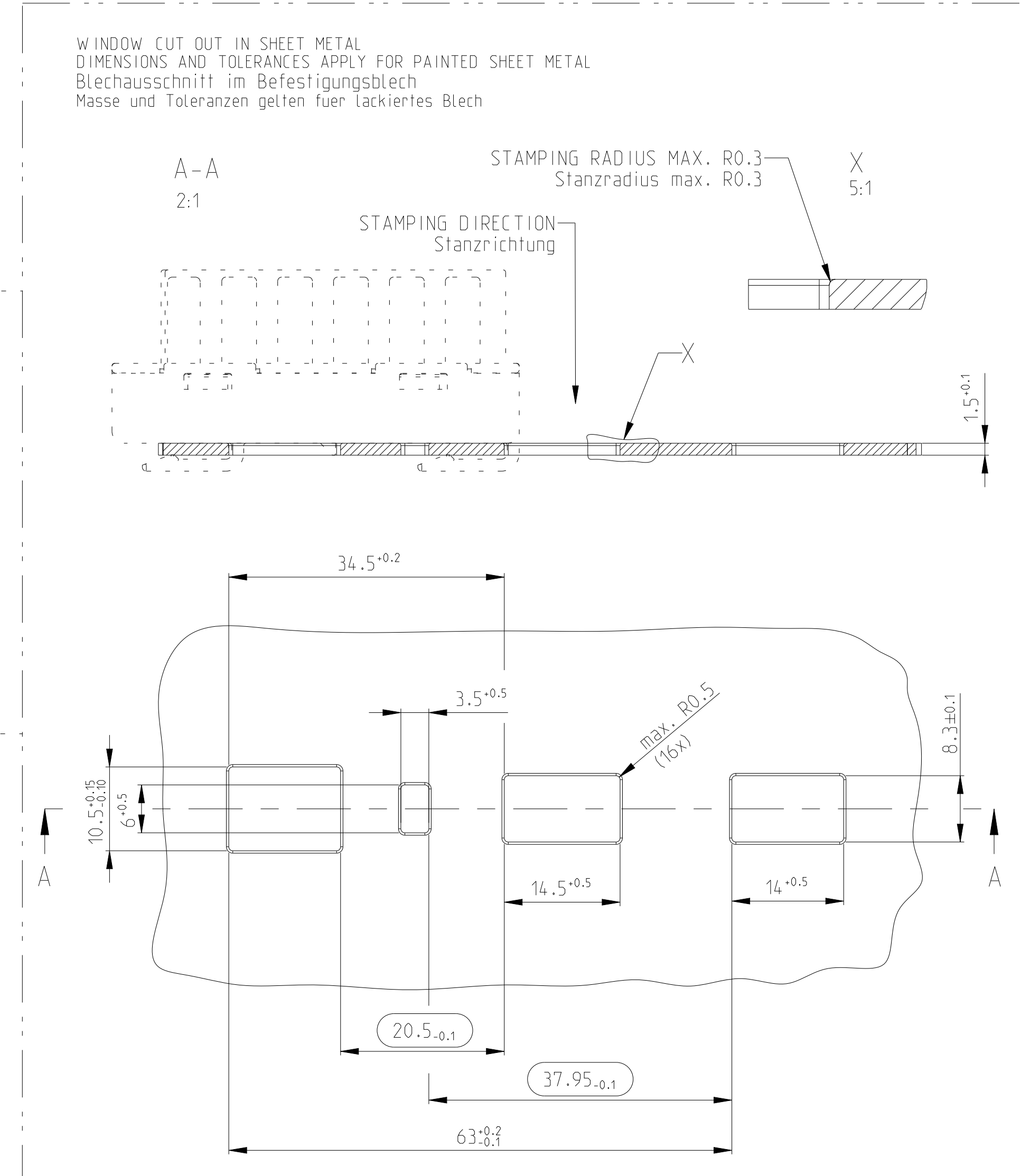
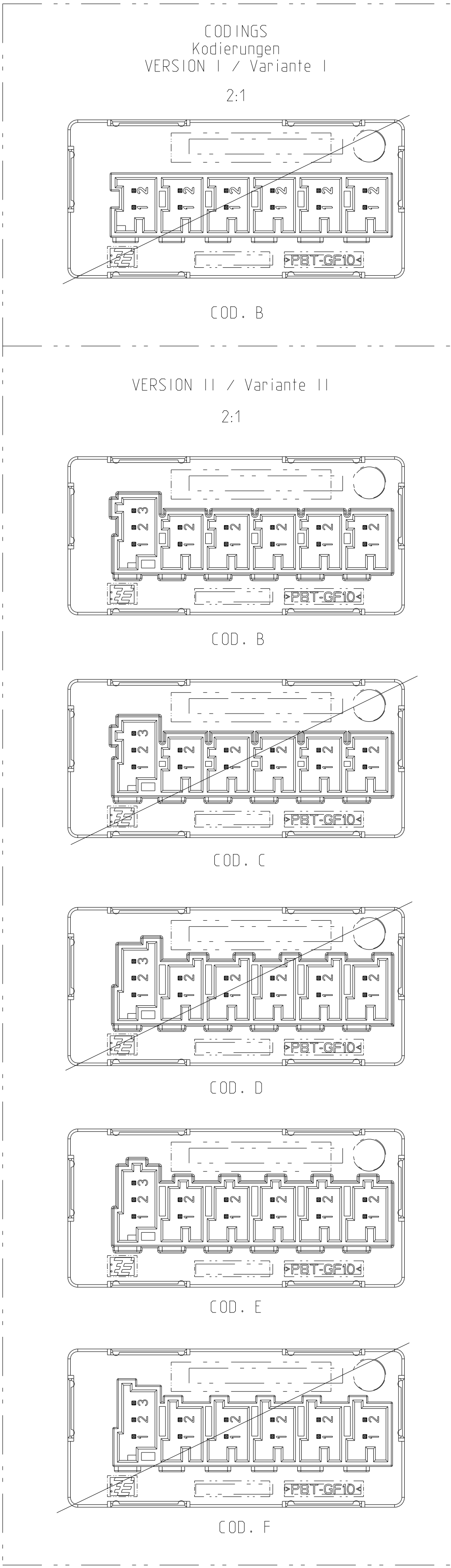
LOC	REV	DATE	BY	APPD
A1	-			
	A	19FEB2010	CR	
	B	09MAY2023	CG	HHC



CONTACT SURFACE 1.0 TO 3.0 µm REFLOWED TINPLATING OVER 1.3 TO 2.2 µm NICKEL
 Kontaktoberfläche der Pins 1,0 bis 3,0 µm Verzinnung ueber 1,3 bis 2,2 µm Nickel



- NOTES
 Bemerkungen
- ONLY THE GERMAN LANGUAGE SHALL BE BINDING
 Massgebend ist der Deutsche Text
 - 2- -1 AS SHOWN
 wie gezeichnet
 - FUNCTIONAL MEASUREMENTS MARKED WITH ARE DOCUMENTED IN THE PPFB. NOT MARKED MEASUREMENTS ARE MEASURED, BUT NOT DOCUMENTED IN THE PPFB. DEVIATIONS HAVE TO BE CORRECTED.
 Funktionsbestimmende Masse, die mit gekennzeichnet sind, werden im PPFB dokumentiert. Nicht gekennzeichnete Masse werden ebenfalls ausgemessen, aber nicht im PPFB dokumentiert. Abweichungen sind zu korrigieren.
- SUPPLIER MARK
 Lieferantenkennzeichnung
 - MANUFACTURING IDENTIFIER
 Herstellungskennung
 - DATE INSERT
 Datumstempel
 - MATERIAL IDENTIFICATION
 Materialbezeichnung
 - CODINGS ACCORDING TO THE CODING DESIGNATION OF THE SPECIFICATION AND THE SUITABLE SOCKET HOUSINGS.
 Kodierungen entsprechen den Kodierungsbezeichnungen der AV und der zugehörigen Buchsengehäuse.
 - SMD-PARTS ON PRINTED CIRCUIT BOARD:
 RESISTORS:
 R1 AND R2 = 56-64 Ω ±1%, 750 mw; R3 = 10 Ω ±5%, 200 mw
 CONDENSER: C1 = 47 nF
 FERRIT CHIPS: K = TDK MHF2012FRC570ATD25
 SMD-Bauteile auf der Leiterplatte:
 Widerstände:
 R1 AND R2 = 56-64 Ω ±1%, 750 mw; R3 = 10 Ω ±5%, 200 mw
 Kondensator: C1 = 47 nF
 Ferritkerne: K = TDK MHF2012FRC570ATD25
 - SMD-PARTS ON PRINTED CIRCUIT BOARD:
 RESISTORS:
 R1 AND R2 = 56-64 Ω ±1%, 250 mw; R3 = 10 Ω ±5%, 200 mw
 CONDENSER: C1 = 47 nF
 SMD-Bauteile auf der Leiterplatte:
 Widerstände:
 R1 AND R2 = 56-64 Ω ±1%, 250 mw; R3 = 10 Ω ±5%, 200 mw
 Kondensator: C1 = 47 nF
 - DIMENSION WAS DETERMINATED DIFFERENT FROM SPECIFICATION 114-18562 AND 114-18563
 Mass abweichend von Ausführvorschrift 114-18562 und 114-18563 festgelegt



NOTE Bem.	FEATURE Merkmal	TE Connectivity - No.
12	AV - INTERFACE AV - Schnittstelle	114-18563
13	AV - INTERFACE AV - Schnittstelle	114-18562
14	USEABLE SOCKET HSG passende Kupplung	14-18640
15	USEABLE SOCKET HSG passende Kupplung	14-18639
16	PRODUCT - SPEC. Produkt - Spez.	108-18861

Benennung TITLE	Masse (kg) MASS (kg)	TE Connectivity Cod	Bestell.-Nr. ORDER-NO.	REV	QTY	Benennung TITLE	Werkstoff MATERIAL	Oberfläche/Farbe SURFACE/COLOR	Pos. ITEM
ENERGIEVERTEILER CAN 5x2/1x3pol.	0.012	e	5-1418637-5	C	1	Leiterplatte, bestückt PRINTED CIRCUIT BOARD	-	-	3
					1	Deckel COVER	PAK-01 30 Durothin B4150	natuP/NATURE	2
					1	Stiftwanne 5x2/1x3pol., MGS PIN HEADER 5X2/1X3POS., MGS	BA52/100000 BA52002	natuP/NATURE	1
ENERGIEVERTEILER CAN 5x2/1x3pol.	0.012	B	2-1418637-5	D	1	Leiterplatte, bestückt PRINTED CIRCUIT BOARD	-	-	3
					1	Deckel COVER	PAK-01 30 Durothin B4150	natuP/NATURE	2
					1	Stiftwanne 5x2/1x3pol., MGS PIN HEADER 5X2/1X3POS., MGS	BA52/100000 BA52002	gruen/GREEN oehl./SIMILAR RAL 6011	1

TE Connectivity
 CAN MODUL 5X2POS. / 1X3POS., ASSY
 Potentialverteiler 5x2pol./1x3pol., Assy
 CASE CODE DRAWING NO. 1418637
 SCALE 1:1
 SHEET 1 OF 1
 REV. B